

180吨自动封装系统 180 TONS MOLDING SYSTEM



Application fields

IC , DEVICE, LQFP, QFN, DFN, BGA and other chips automatic molding.

Hardware configuration

1. Applicable lead frame size: W: 20-108mm L: 124-300mm T: 0.1-0.6mm.
2. Resin diameter: $\phi 11 \sim \phi 20\text{mm}$ ($\pm 0.2\text{mm}$), Length to diameter ratio of resin: length/diameter=1.2-1.7 (Max 35mm)
3. Multiple detection methods such as whether the material is present or not, positive or negative.
4. Modular design, achieving free combination of loading unit, press unit, and unloading unit, suitable for 1-4 press units.
5. Options include vacuum packaging, FILM packaging, and suitable for copper based, iron based, circuit board, and other substrate packaging materials.
6. Automatic loading, automatic packaging, and automatic collecting.

Software features

1. For the detected positive and negative objects, an alarm reminder will be given for the foreign object product.
2. Inspection of loading, unloading, and collecting processes;
3. Provide an explanation of abnormal alarms and display corresponding handling methods.

技术参数 TECHNICAL PARAMETER				
适用I/F尺寸 I/F SIZE APPLICABLE	封装数量 NUMBER OF PACKAGES	压机数量 NUMBER OF PRESSES	合模压力 CLAMPING PRESSURE	注塑压力 INJECTION PRESSURE
宽: 20-105mm/长: 124-310mm 厚: 0.1-0.6mm	2 L/F/次/压机	1~4个压机	98~1,764KN 最大180吨	4.9~39.4KN 最大4吨